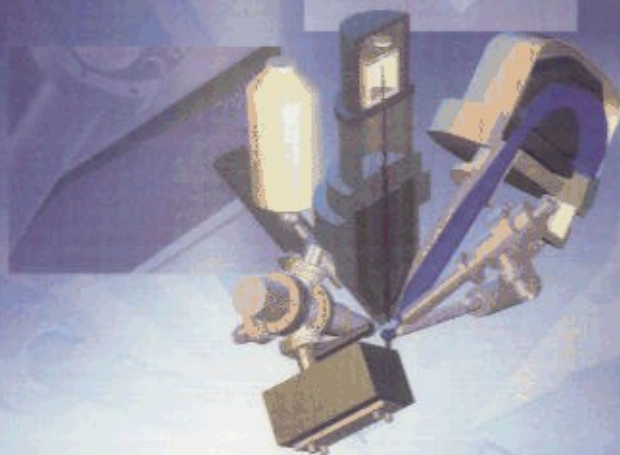


An Introduction to **SURFACE ANALYSIS** by XPS and AES

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